

ABSTRACT

A method and apparatus for achieving a consistent depth of immersion of a semiconductor element into an exposed surface of an adhesive material pool when applying the adhesive material, conductive or non-conductive, to the semiconductor element or portion thereof. The consistent depth of immersion is defined by a stop which is attached to a reservoir used to form the adhesive material pool, attached to a stencil which is used in conjunction with the reservoir to form a level upper surface on the adhesive material, or operates independently from the reservoir and/or stencil.

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